

## 1A, 200V - 1000V High Efficient Surface Mount Rectifier

### FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	1	A
$V_{RRM}$	200 - 1000	V
$I_{FSM}$	35	A
$T_{J\ MAX}$	150	°C
Package	Thin SMA	
Configuration	Single die	

### APPLICATIONS

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application



Thin SMA



### MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.029g (approximately)

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)								
PARAMETER	SYMBOL	HS1D ALH	HS1G ALH	HS1J ALH	HS1K ALH	HS1M ALH	UNIT	
Marking code on the device		HS1DAH	HS1GAH	HS1JAH	HS1KAH	HS1MAH		
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V	
Forward current	$I_F$	1						A
Surge peak forward current, single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	$I_{FSM}$						A
	$t = 1.0\text{ms}$	90						A
Junction temperature	$T_J$	-55 to +150						°C
Storage temperature	$T_{STG}$	-55 to +150						°C

<b>THERMAL PERFORMANCE</b>			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	29	$^{\circ}C/W$
Junction-to-ambient thermal resistance	$R_{\theta JA}$	51	$^{\circ}C/W$
Junction-to-case thermal resistance	$R_{\theta JC}$	22	$^{\circ}C/W$

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^{\circ}C$ unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	HS1DALH	$I_F = 0.5A, T_J = 25^{\circ}C$	$V_F$	0.80	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		0.85	1.00	V
		$I_F = 0.5A, T_J = 125^{\circ}C$		0.65	-	V
		$I_F = 1.0A, T_J = 125^{\circ}C$		0.71	0.80	V
	HS1GALH	$I_F = 0.5A, T_J = 25^{\circ}C$		0.84	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		0.91	1.30	V
		$I_F = 0.5A, T_J = 125^{\circ}C$		0.68	-	V
		$I_F = 1.0A, T_J = 125^{\circ}C$		0.76	0.86	V
	HS1JALH	$I_F = 0.5A, T_J = 25^{\circ}C$		0.92	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		1.02	1.70	V
		$I_F = 0.5A, T_J = 125^{\circ}C$		0.73	-	V
		$I_F = 1.0A, T_J = 125^{\circ}C$		0.83	1.02	V
	HS1KALH HS1MALH	$I_F = 0.5A, T_J = 25^{\circ}C$		1.32	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		1.49	1.70	V
		$I_F = 0.5A, T_J = 125^{\circ}C$		0.98	-	V
		$I_F = 1.0A, T_J = 125^{\circ}C$		1.16	1.39	V
Reverse current @ rated $V_R$ <sup>(2)</sup>		$T_J = 25^{\circ}C$	$I_R$	-	1	$\mu A$
		$T_J = 125^{\circ}C$		-	35	$\mu A$
Reverse recovery time		$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	$t_{rr}$	-	50	ns
					-	75
Junction capacitance		1MHz, $V_R = 4.0V$	$C_J$	20	-	pF
				17	-	pF
				13	-	pF
				8	-	pF

**Notes:**

1. Pulse test with PW = 0.3ms
2. Pulse test with PW = 30ms

<b>ORDERING INFORMATION</b>		
<b>ORDERING CODE<sup>(1)</sup></b>	<b>PACKAGE</b>	<b>PACKING</b>
HS1xALH	Thin SMA	14,000 / Tape & Reel

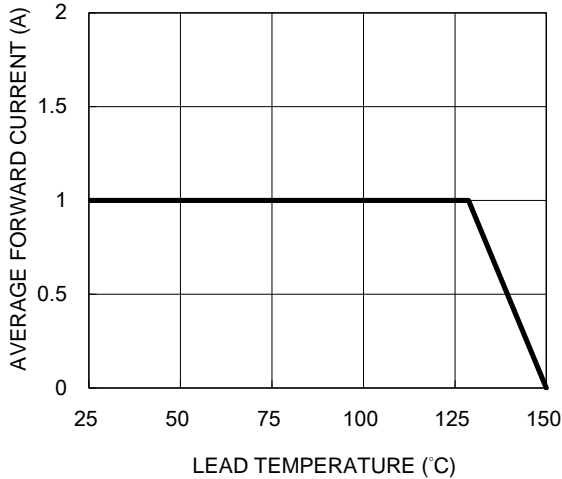
**Notes:**

1. “x” defines voltage from 200V(HS1DALH) to 1000V(HS1MALH)

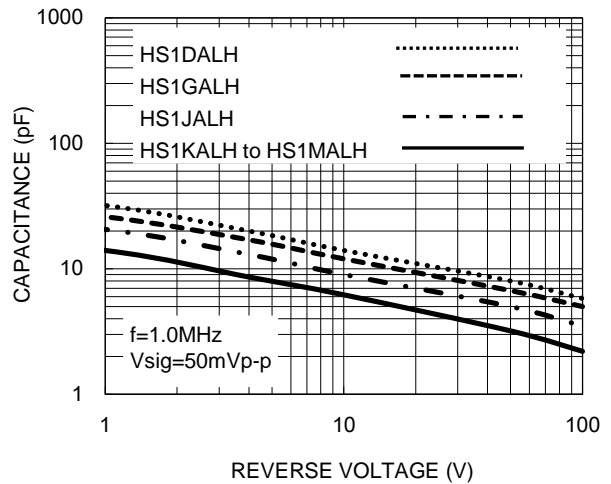
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

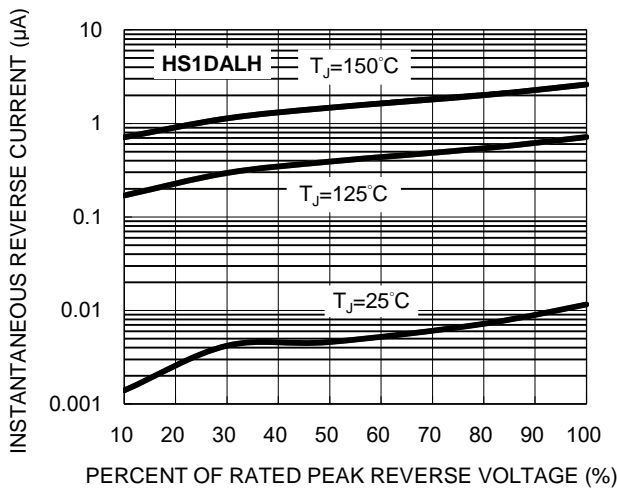
**Fig.1 Forward Current Derating Curve**



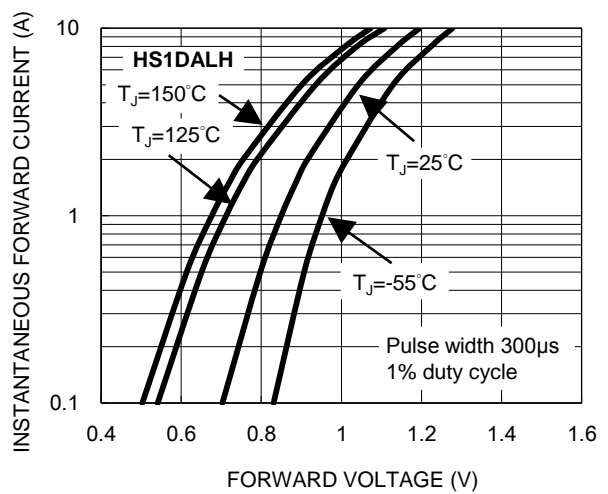
**Fig.2 Typical Junction Capacitance**



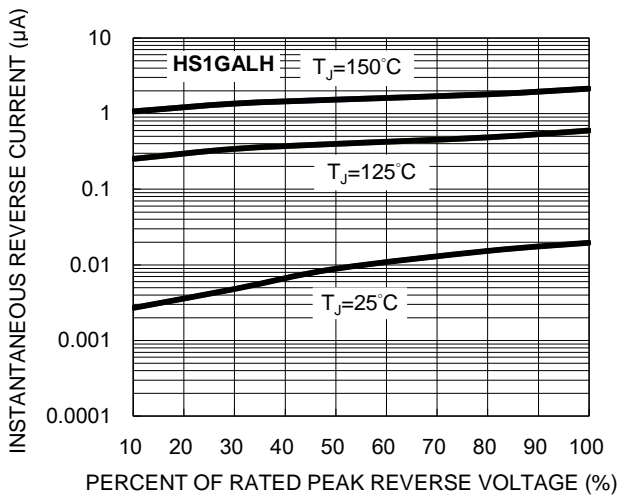
**Fig.3 Typical Reverse Characteristics**



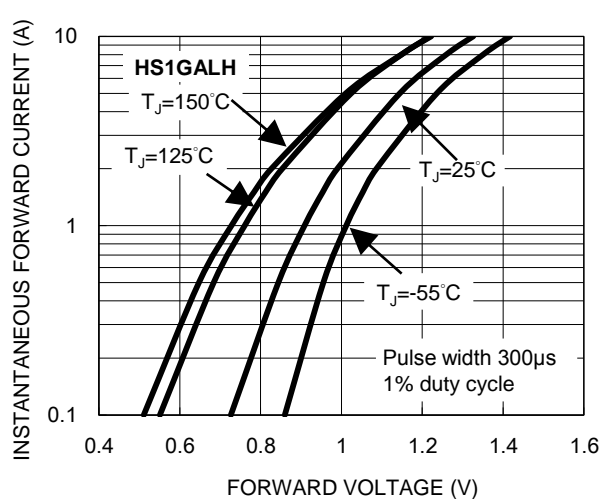
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Reverse Characteristics**



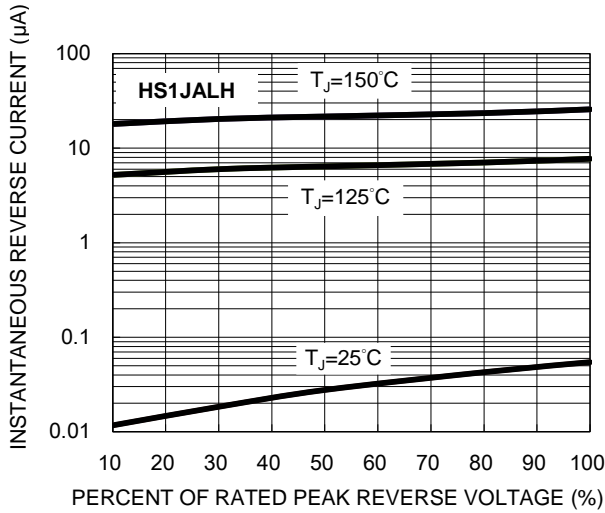
**Fig.6 Typical Forward Characteristics**



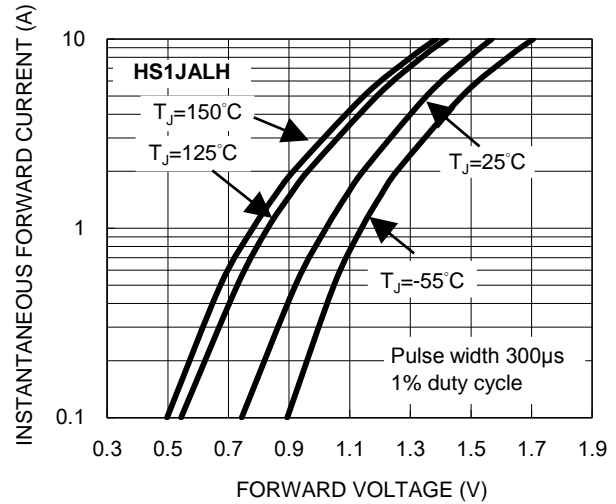
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

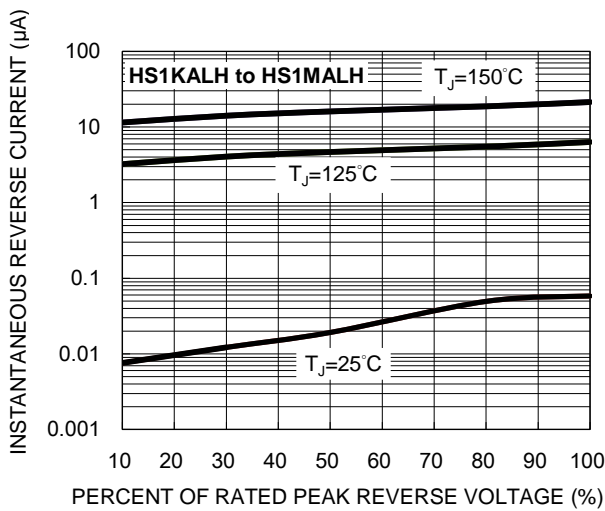
**Fig.7 Typical Reverse Characteristics**



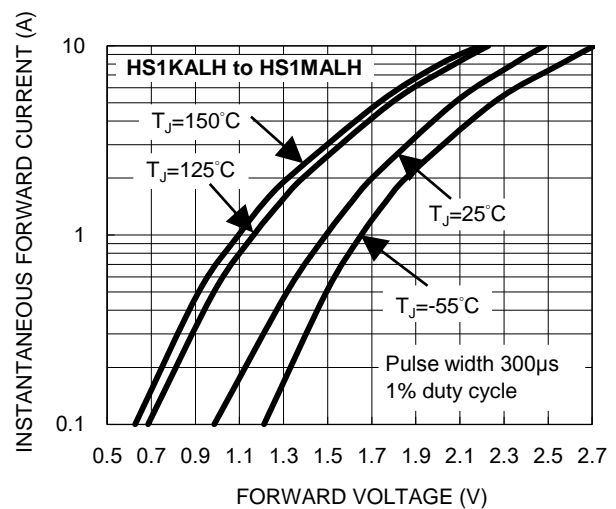
**Fig.8 Typical Forward Characteristics**



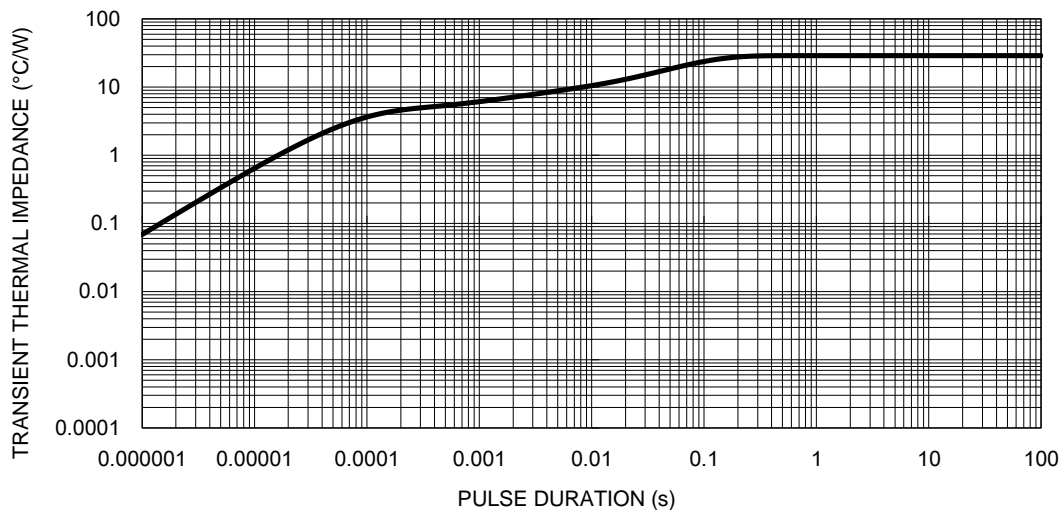
**Fig.9 Typical Reverse Characteristics**



**Fig.10 Typical Forward Characteristics**

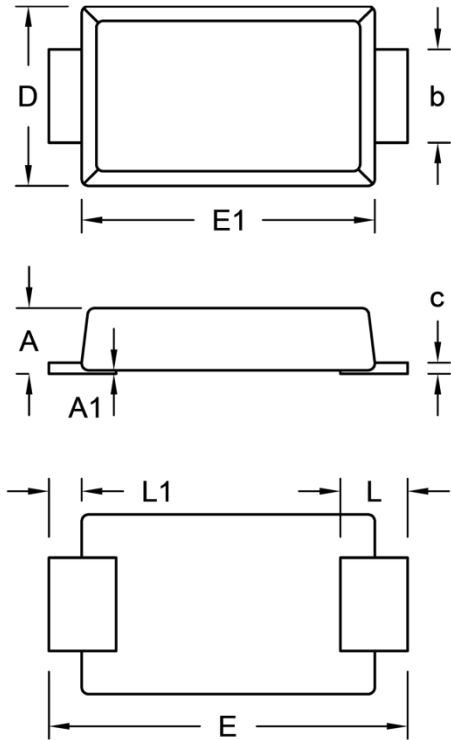


**Fig.11 Typical Transient Thermal Impedance**



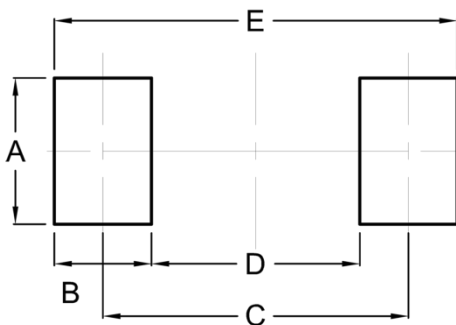
**PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.90	1.00	0.035	0.039
A1	0.00	0.10	0.000	0.004
b	1.25	1.45	0.049	0.057
c	0.10	0.22	0.004	0.009
D	2.50	2.70	0.098	0.106
E	5.05	5.35	0.199	0.211
E1	4.15	4.35	0.163	0.171
L	0.75	1.20	0.030	0.047
L1	0.30	0.60	0.012	0.024

**SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
A	2.10	0.083
B	1.40	0.055
C	4.40	0.173
D	3.00	0.118
E	5.80	0.228

**MARKING DIAGRAM**



P/N = Marking Code  
 YW = Date Code  
 F = Factory Code

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